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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	67
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 22x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep128gs808-e-pt

REGISTER 3-1: SR: CPU STATUS REGISTER (CONTINUED)

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits[1,2]

111 = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

bit 4 **RA:** REPEAT Loop Active bit

1 = REPEAT loop is in progress
0 = REPEAT loop is not in progress

bit 3 **N:** MCU ALU Negative bit

1 = Result was negative
0 = Result was non-negative (zero or positive)

bit 2 **OV:** MCU ALU Overflow bit

This bit is used for signed arithmetic (2's complement). It indicates an overflow of the magnitude that causes the sign bit to change state.
1 = Overflow occurred for signed arithmetic (in this arithmetic operation)
0 = No overflow occurred

bit 1 **Z:** MCU ALU Zero bit

1 = An operation that affects the Z bit has set it at some time in the past
0 = The most recent operation that affects the Z bit has cleared it (i.e., a non-zero result)

bit 0 **C:** MCU ALU Carry/$\overline{\text{Borrow}}$ bit

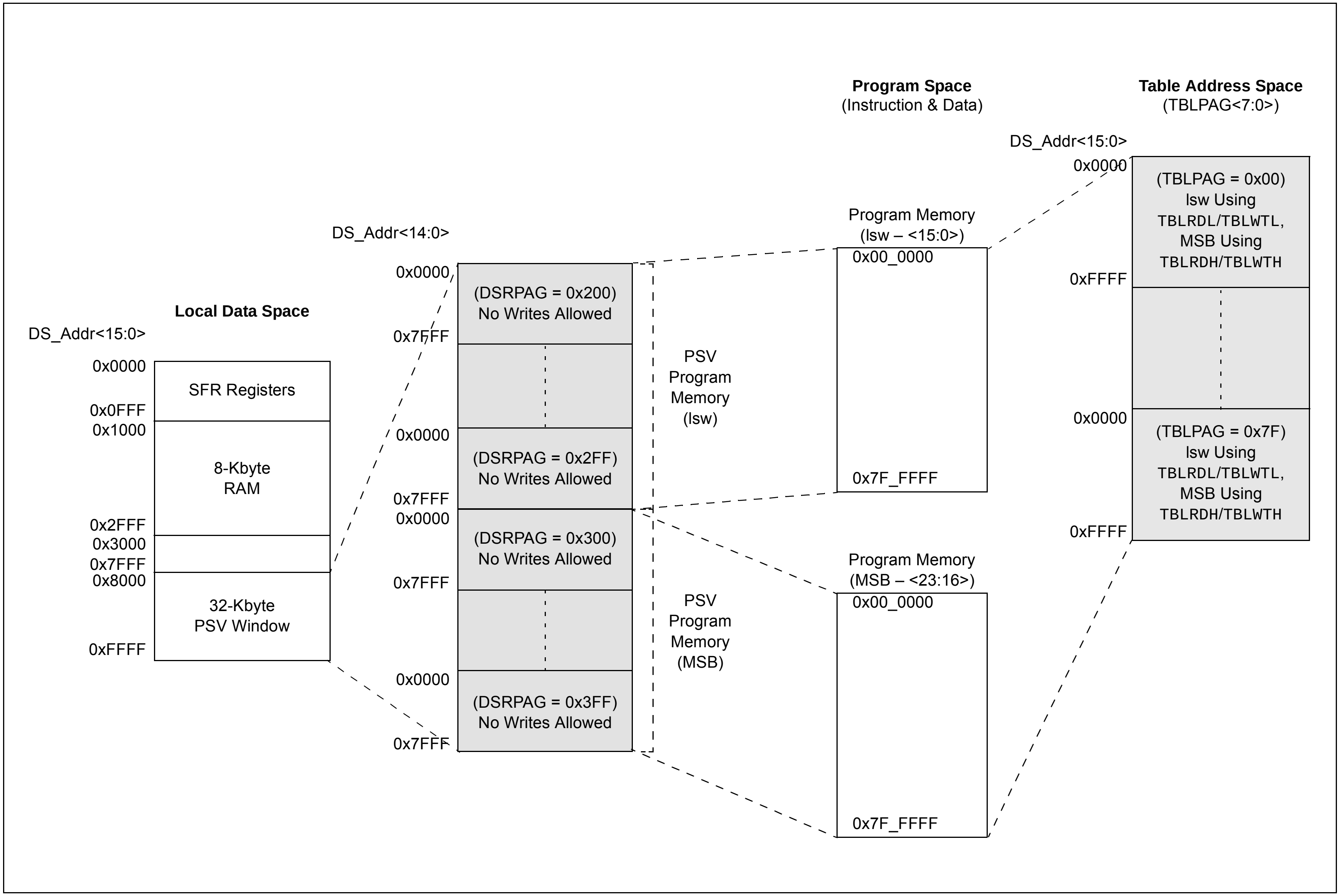
1 = A carry-out from the Most Significant bit of the result occurred
0 = No carry-out from the Most Significant bit of the result occurred

Note 1: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL, if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.

2: The IPL<2:0> Status bits are read-only when the NSTDIS bit (INTCON1<15>) = 1.

3: A data write to the SR register can modify the SA and SB bits by either a data write to SA and SB or by clearing the SAB bit. To avoid a possible SA or SB bit write race condition, the SA and SB bits should not be modified using bit operations.

FIGURE 4-8: PAGED DATA MEMORY SPACE



REGISTER 7-5: INTCON3: INTERRUPT CONTROL REGISTER 3

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	NAE
bit 15							bit 8

U-0	U-0	U-0	R/W-0	U-0	U-0	U-0	R/W-0
—	—	—	DOOVR	—	—	—	APLL
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as ‘0’

bit 8 **NAE:** NVM Address Error Soft Trap Status bit
1 = NVM address error soft trap has occurred
0 = NVM address error soft trap has not occurred

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4 **DOOVR:** DO Stack Overflow Soft Trap Status bit
1 = DO stack overflow soft trap has occurred
0 = DO stack overflow soft trap has not occurred

bit 3-1 **Unimplemented:** Read as ‘0’

bit 0 **APLL:** Auxiliary PLL Loss of Lock Soft Trap Status bit
1 = APLL lock soft trap has occurred
0 = APLL lock soft trap has not occurred

REGISTER 7-6: INTCON4: INTERRUPT CONTROL REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	SGHT
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-1 **Unimplemented:** Read as ‘0’

bit 0 **SGHT:** Software Generated Hard Trap Status bit
1 = Software generated hard trap has occurred
0 = Software generated hard trap has not occurred

REGISTER 10-7: PMD8: PERIPHERAL MODULE DISABLE CONTROL REGISTER 8

U-0	U-0	U-0	U-0	U-0	R/W-0	U-0	U-0
—	—	—	—	—	PGA2MD	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
—	—	CLC4MD	CLC3MD	CLC2MD	CLC1MD	CCSMD	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as ‘0’

bit 10 **PGA2MD:** PGA2 Module Disable bit
1 = PGA2 module is disabled
0 = PGA2 module is enabled

bit 9-6 **Unimplemented:** Read as ‘0’

bit 5 **CLC4MD:** CLC4 Module Disable bit
1 = CLC4 module is disabled
0 = CLC4 module is enabled

bit 4 **CLC3MD:** CLC3 Module Disable bit
1 = CLC3 module is disabled
0 = CLC3 module is enabled

bit 3 **CLC2MD:** CLC2 Module Disable bit
1 = CLC2 module is disabled
0 = CLC2 module is enabled

bit 2 **CLC1MD:** CLC1 Module Disable bit
1 = CLC1 module is disabled
0 = CLC1 module is enabled

bit 1 **CCSMD:** Constant-Current Source Module Disable bit
1 = Constant-current source module is disabled
0 = Constant-current source module is enabled

bit 0 **Unimplemented:** Read as ‘0’

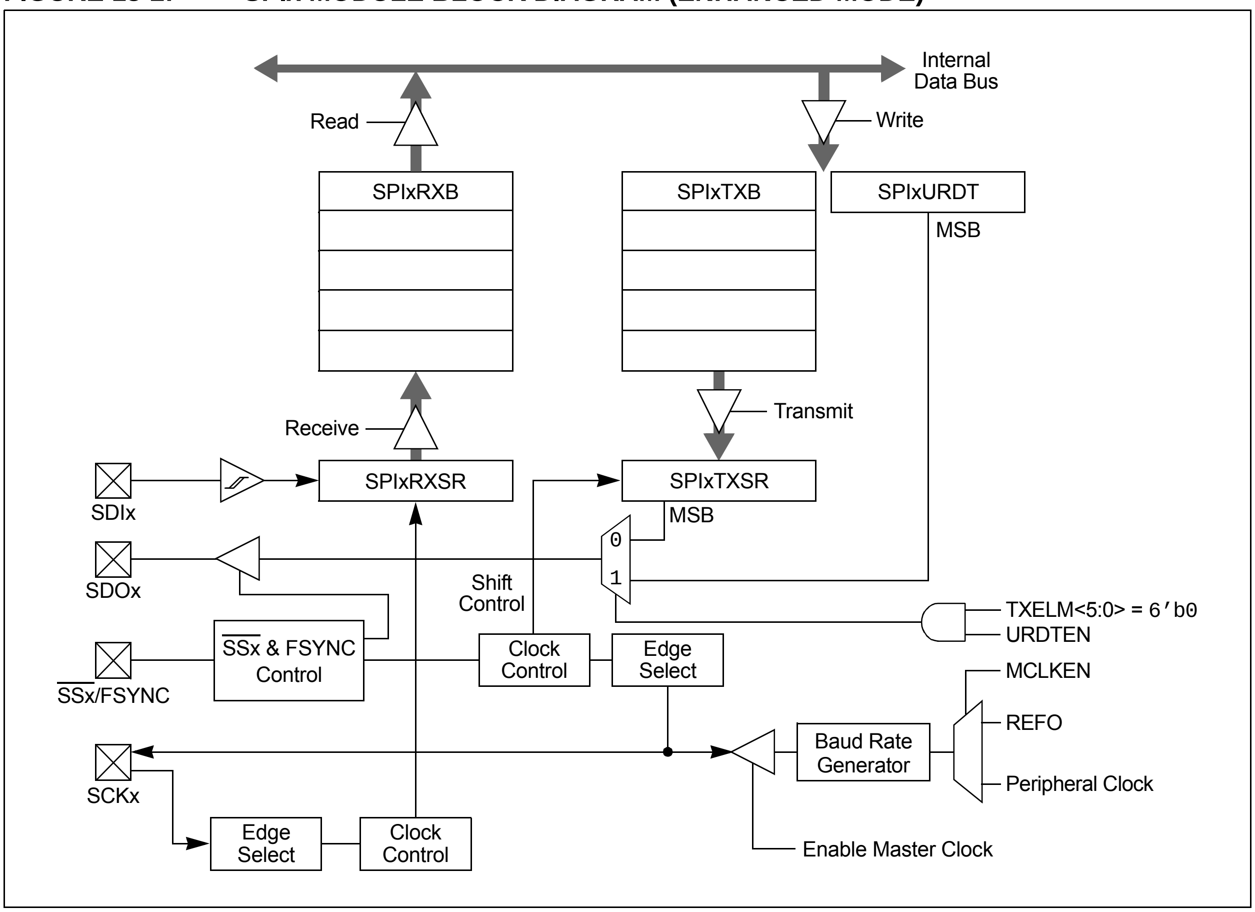
To set up the SPIx module for the Enhanced Buffer Master mode of operation:

1. If using interrupts:
   a) Clear the interrupt flag bits in the respective IFSx register.
   b) Set the interrupt enable bits in the respective IECx register.
   c) Write the SPIxIP bits in the respective IPCx register.
2. Write the desired settings to the SPIxCON1L, SPIxCON1H and SPIxCON2L registers with MSTEN (SPIxCON1L<5>) = `1`.
3. Clear the SPIROV bit (SPIxSTATL<6>).
4. Select Enhanced Buffer mode by setting the ENHBUF bit (SPIxCON1L<0>).
5. Enable SPIx operation by setting the SPIEN bit (SPIxCON1L<15>).
6. Write the data to be transmitted to the SPIxBUFL and SPIxBUFH registers. Transmission (and reception) will start as soon as data is written to the SPIxBUFL and SPIxBUFH registers.

To set up the SPIx module for the Enhanced Buffer Slave mode of operation:

1. Clear the SPIxBUFL and SPIxBUFH registers.
2. If using interrupts:
   a) Clear the interrupt flag bits in the respective IFSx register.
   b) Set the interrupt enable bits in the respective IECx register.
   c) Write the SPIxIP bits in the respective IPCx register to set the interrupt priority.
3. Write the desired settings to the SPIxCON1L, SPIxCON1H and SPIxCON2L registers with the MSTEN bit (SPIxCON1L<5>) = `0`.
4. Clear the SMP bit.
5. If the CKE bit is set, then the SSEN bit must be set, thus enabling the $\overline{\text{SSx}}$ pin.
6. Clear the SPIROV bit (SPIxSTATL<6>).
7. Select Enhanced Buffer mode by setting the ENHBUF bit (SPIxCON1L<0>).
8. Enable SPIx operation by setting the SPIEN bit (SPIxCON1L<15>).

FIGURE 18-2: SPIx MODULE BLOCK DIAGRAM (ENHANCED MODE)



REGISTER 21-1: CLCxCONL: CLCx CONTROL REGISTER (LOW) (CONTINUED)

bit 2-0 **MODE<2:0>:** CLCx Mode bits
111 = Single Input Transparent Latch with S and R
110 = JK Flip-Flop with R
101 = Two-Input D Flip-Flop with R
100 = Single Input D Flip-Flop with S and R
011 = SR Latch
010 = Four-Input AND
001 = Four-Input OR-XOR
000 = Four-Input AND-OR

REGISTER 21-2: CLCxCONH: CLCx CONTROL REGISTER (HIGH)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	G4POL	G3POL	G2POL	G1POL
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-4 **Unimplemented:** Read as ‘0’

bit 3 **G4POL:** Gate 4 Polarity Control bit
1 = Channel 4 logic output is inverted when applied to the logic cell
0 = Channel 4 logic output is not inverted

bit 2 **G3POL:** Gate 3 Polarity Control bit
1 = Channel 3 logic output is inverted when applied to the logic cell
0 = Channel 3 logic output is not inverted

bit 1 **G2POL:** Gate 2 Polarity Control bit
1 = Channel 2 logic output is inverted when applied to the logic cell
0 = Channel 2 logic output is not inverted

bit 0 **G1POL:** Gate 1 Polarity Control bit
1 = Channel 1 logic output is inverted when applied to the logic cell
0 = Channel 1 logic output is not inverted

REGISTER 21-5: CLCxGLSH: CLCx GATE LOGIC INPUT SELECT HIGH REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
G4D4T	G4D4N	G4D3T	G4D3N	G4D2T	G4D2N	G4D1T	G4D1N
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
G3D4T	G3D4N	G3D3T	G3D3N	G3D2T	G3D2N	G3D1T	G3D1N
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **G4D4T:** Gate 4 Data Source 4 True Enable bit
1 = Data Source 4 non-inverted signal is enabled for Gate 4
0 = Data Source 4 non-inverted signal is disabled for Gate 4

bit 14 **G4D4N:** Gate 4 Data Source 4 Negated Enable bit
1 = Data Source 4 inverted signal is enabled for Gate 4
0 = Data Source 4 inverted signal is disabled for Gate 4

bit 13 **G4D3T:** Gate 4 Data Source 3 True Enable bit
1 = Data Source 3 non-inverted signal is enabled for Gate 4
0 = Data Source 3 non-inverted signal is disabled for Gate 4

bit 12 **G4D3N:** Gate 4 Data Source 3 Negated Enable bit
1 = Data Source 3 inverted signal is enabled for Gate 4
0 = Data Source 3 inverted signal is disabled for Gate 4

bit 11 **G4D2T:** Gate 4 Data Source 2 True Enable bit
1 = Data Source 2 non-inverted signal is enabled for Gate 4
0 = Data Source 2 non-inverted signal is disabled for Gate 4

bit 10 **G4D2N:** Gate 4 Data Source 2 Negated Enable bit
1 = Data Source 2 inverted signal is enabled for Gate 4
0 = Data Source 2 inverted signal is disabled for Gate 4

bit 9 **G4D1T:** Gate 4 Data Source 1 True Enable bit
1 = Data Source 1 non-inverted signal is enabled for Gate 4
0 = Data Source 1 non-inverted signal is disabled for Gate 4

bit 8 **G4D1N:** Gate 4 Data Source 1 Negated Enable bit
1 = Data Source 1 inverted signal is enabled for Gate 4
0 = Data Source 1 inverted signal is disabled for Gate 4

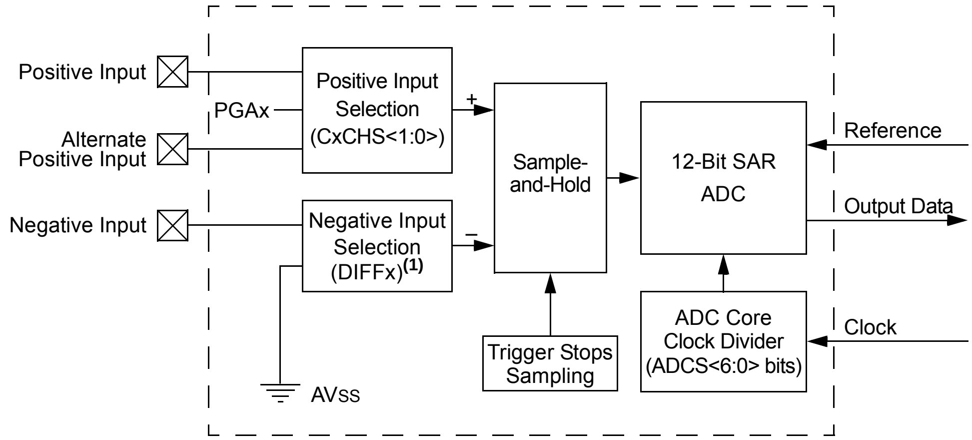
bit 7 **G3D4T:** Gate 3 Data Source 4 True Enable bit
1 = Data Source 4 non-inverted signal is enabled for Gate 3
0 = Data Source 4 non-inverted signal is disabled for Gate 3

bit 6 **G3D4N:** Gate 3 Data Source 4 Negated Enable bit
1 = Data Source 4 inverted signal is enabled for Gate 3
0 = Data Source 4 inverted signal is disabled for Gate 3

bit 5 **G3D3T:** Gate 3 Data Source 3 True Enable bit
1 = Data Source 3 non-inverted signal is enabled for Gate 3
0 = Data Source 3 non-inverted signal is disabled for Gate 3

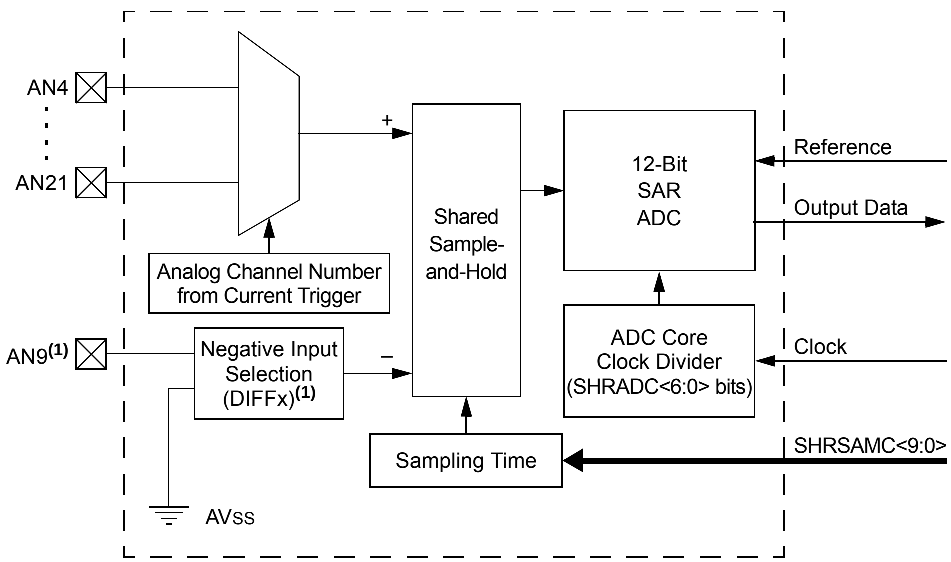
bit 4 **G3D3N:** Gate 3 Data Source 3 Negated Enable bit
1 = Data Source 3 inverted signal is enabled for Gate 3
0 = Data Source 3 inverted signal is disabled for Gate 3

FIGURE 22-2: DEDICATED ADC CORES 0 TO 3 BLOCK DIAGRAM



Note 1: The DIFFx bit for the corresponding positive input channel must be set in order to use the negative differential input.

FIGURE 22-3: SHARED ADC CORE BLOCK DIAGRAM



Note 1: Differential-mode conversion is not available for the shared ADC core in dsPIC33EPXXGS70X/80X devices. For all other devices, the DIFFx bit for the corresponding positive input channel must be set to use AN9 as the negative differential input.

REGISTER 22-26: ADTRIGxL: ADC CHANNEL TRIGGER x SELECTION REGISTER LOW (x = 0 to 5) (CONTINUED)

bit 4-0 **TRGSRC(4x)<4:0>:** Trigger Source Selection for Corresponding Analog Inputs bits

`11111` = ADTRG31
`11110` = PTG Trigger Output 30
`11101` = PWM Generator 6 current-limit trigger
`11100` = PWM Generator 5 current-limit trigger
`11011` = PWM Generator 4 current-limit trigger
`11010` = PWM Generator 3 current-limit trigger
`11001` = PWM Generator 2 current-limit trigger
`11000` = PWM Generator 1 current-limit trigger
`10111` = Output Compare 2 trigger
`10110` = Output Compare 1 trigger
`10101` = CLC2 output
`10100` = PWM Generator 6 secondary trigger
`10011` = PWM Generator 5 secondary trigger
`10010` = PWM Generator 4 secondary trigger
`10001` = PWM Generator 3 secondary trigger
`10000` = PWM Generator 2 secondary trigger
`01111` = PWM Generator 1 secondary trigger
`01110` = PWM secondary Special Event Trigger
`01101` = Timer2 period match
`01100` = Timer1 period match
`01011` = CLC1 output
`01010` = PWM Generator 6 primary trigger
`01001` = PWM Generator 5 primary trigger
`01000` = PWM Generator 4 primary trigger
`00111` = PWM Generator 3 primary trigger
`00110` = PWM Generator 2 primary trigger
`00101` = PWM Generator 1 primary trigger
`00100` = PWM Special Event Trigger
`00011` = Reserved
`00010` = Level software trigger
`00001` = Common software trigger
`00000` = No trigger is enabled

REGISTER 22-34: ADFLxCON: ADC DIGITAL FILTER x CONTROL REGISTER (x = 0 or 1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0, HSC
FLEN	MODE1	MODE0	OVRSAM2	OVRSAM1	OVRSAM0	IE	RDY
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	FLCHSEL4	FLCHSEL3	FLCHSEL2	FLCHSEL1	FLCHSEL0
bit 7							bit 0

Legend:	U = Unimplemented bit, read as ‘0’		
R = Readable bit	W = Writable bit	HSC = Hardware Settable/Clearable bit	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **FLEN:** Filter Enable bit
1 = Filter is enabled
0 = Filter is disabled and the RDY bit is cleared

bit 14-13 **MODE<1:0>:** Filter Mode bits
11 = Averaging mode
10 = Reserved
01 = Reserved
00 = Oversampling mode

bit 12-10 **OVRSAM<2:0>:** Filter Averaging/Oversampling Ratio bits
If MODE<1:0> = 00:
111 = 128x (16-bit result in the ADFLxDAT register is in 12.4 format)
110 = 32x (15-bit result in the ADFLxDAT register is in 12.3 format)
101 = 8x (14-bit result in the ADFLxDAT register is in 12.2 format)
100 = 2x (13-bit result in the ADFLxDAT register is in 12.1 format)
011 = 256x (16-bit result in the ADFLxDAT register is in 12.4 format)
010 = 64x (15-bit result in the ADFLxDAT register is in 12.3 format)
001 = 16x (14-bit result in the ADFLxDAT register is in 12.2 format)
000 = 4x (13-bit result in the ADFLxDAT register is in 12.1 format)
If MODE<1:0> = 11 (12-bit result in the ADFLxDAT register in all instances):
111 = 256x
110 = 128x
101 = 64x
100 = 32x
011 = 16x
010 = 8x
001 = 4x
000 = 2x

bit 9 **IE:** Filter Common ADC Interrupt Enable bit
1 = Common ADC interrupt will be generated when the filter result will be ready
0 = Common ADC interrupt will not be generated for the filter

bit 8 **RDY:** Oversampling Filter Data Ready Flag bit
This bit is cleared by hardware when the result is read from the ADFLxDAT register.
1 = Data in the ADFLxDAT register is ready
0 = The ADFLxDAT register has been read and new data in the ADFLxDAT register is not ready

bit 7-5 **Unimplemented:** Read as ‘0’

REGISTER 23-5: CxFIFO: CANx FIFO STATUS REGISTER

U-0	U-0	R-0	R-0	R-0	R-0	R-0	R-0
—	—	FBP5	FBP4	FBP3	FBP2	FBP1	FBP0
bit 15							bit 8

U-0	U-0	R-0	R-0	R-0	R-0	R-0	R-0
—	—	FNRB5	FNRB4	FNRB3	FNRB2	FNRB1	FNRB0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **FBP<5:0>:** FIFO Buffer Pointer bits
011111 = RB31 buffer
011110 = RB30 buffer
•
•
•
000001 = TRB1 buffer
000000 = TRB0 buffer

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **FNRB<5:0>:** FIFO Next Read Buffer Pointer bits
011111 = RB31 buffer
011110 = RB30 buffer
•
•
•
000001 = TRB1 buffer
000000 = TRB0 buffer

REGISTER 23-20: CxRXMnSID: CANx ACCEPTANCE FILTER MASK n STANDARD IDENTIFIER REGISTER (n = 0-2)

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID10	SID9	SID8	SID7	SID6	SID5	SID4	SID3
bit 15							bit 8

R/W-x	R/W-x	R/W-x	U-0	R/W-x	U-0	R/W-x	R/W-x
SID2	SID1	SID0	—	MIDE	—	EID17	EID16
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-5 **SID<10:0>:** Standard Identifier bits
1 = Includes bit, SIDx, in filter comparison
0 = Bit, SIDx, is a don’t care in filter comparison

bit 4 **Unimplemented:** Read as ‘0’

bit 3 **MIDE:** Identifier Receive Mode bit
1 = Matches only message types (standard or extended address) that correspond to the EXIDE bit in the filter
0 = Matches either standard or extended address message if filters match
(i.e., if (Filter SIDx) = (Message SIDx) or if (Filter SIDx/EIDx) = (Message SIDx/EIDx))

bit 2 **Unimplemented:** Read as ‘0’

bit 1-0 **EID<17:16>:** Extended Identifier bits
1 = Includes bit, EIDx, in filter comparison
0 = Bit, EIDx, is a don’t care in filter comparison

REGISTER 23-21: CxRXMnEID: CANx ACCEPTANCE FILTER MASK n EXTENDED IDENTIFIER REGISTER (n = 0-2)

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID<15:8>							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **EID<15:0>:** Extended Identifier bits
1 = Includes bit, EIDx, in filter comparison
0 = Bit, EIDx, is a don’t care in filter comparison

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles[(1)]	Status Flags Affected
55	NEG	NEG Acc	Negate Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
		NEG f	f = $\overline{f}$ + 1	1	1	C,DC,N,OV,Z
		NEG f,WREG	WREG = $\overline{f}$ + 1	1	1	C,DC,N,OV,Z
		NEG Ws,Wd	Wd = $\overline{Ws}$ + 1	1	1	C,DC,N,OV,Z
56	NOP	NOP	No Operation	1	1	None
		NOPR	No Operation	1	1	None
57	POP	POP f	Pop f from Top-of-Stack (TOS)	1	1	None
		POP Wdo	Pop from Top-of-Stack (TOS) to Wdo	1	1	None
		POP.D Wnd	Pop from Top-of-Stack (TOS) to W(nd):W(nd + 1)	1	2	None
		POP.S	Pop Shadow Registers	1	1	All
58	PUSH	PUSH f	Push f to Top-of-Stack (TOS)	1	1	None
		PUSH Wso	Push Wso to Top-of-Stack (TOS)	1	1	None
		PUSH.D Wns	Push W(ns):W(ns + 1) to Top-of-Stack (TOS)	1	2	None
		PUSH.S	Push Shadow Registers	1	1	None
59	PWRSAV	PWRSAV #lit1	Go into Sleep or Idle mode	1	1	WDTO,Sleep
60	RCALL	RCALL Expr	Relative Call	1	4	SFA
		RCALL Wn	Computed Call	1	4	SFA
61	REPEAT	REPEAT #lit15	Repeat Next Instruction lit15 + 1 times	1	1	None
		REPEAT Wn	Repeat Next Instruction (Wn) + 1 times	1	1	None
62	RESET	RESET	Software device Reset	1	1	None
63	RETFIE	RETFIE	Return from interrupt	1	6 (5)	SFA
64	RETLW	RETLW #lit10,Wn	Return with literal in Wn	1	6 (5)	SFA
65	RETURN	RETURN	Return from Subroutine	1	6 (5)	SFA
66	RLC	RLC f	f = Rotate Left through Carry f	1	1	C,N,Z
		RLC f,WREG	WREG = Rotate Left through Carry f	1	1	C,N,Z
		RLC Ws,Wd	Wd = Rotate Left through Carry Ws	1	1	C,N,Z
67	RLNC	RLNC f	f = Rotate Left (No Carry) f	1	1	N,Z
		RLNC f,WREG	WREG = Rotate Left (No Carry) f	1	1	N,Z
		RLNC Ws,Wd	Wd = Rotate Left (No Carry) Ws	1	1	N,Z
68	RRC	RRC f	f = Rotate Right through Carry f	1	1	C,N,Z
		RRC f,WREG	WREG = Rotate Right through Carry f	1	1	C,N,Z
		RRC Ws,Wd	Wd = Rotate Right through Carry Ws	1	1	C,N,Z
69	RRNC	RRNC f	f = Rotate Right (No Carry) f	1	1	N,Z
		RRNC f,WREG	WREG = Rotate Right (No Carry) f	1	1	N,Z
		RRNC Ws,Wd	Wd = Rotate Right (No Carry) Ws	1	1	N,Z
70	SAC	SAC Acc,#Slit4,Wdo	Store Accumulator	1	1	None
		SAC.R Acc,#Slit4,Wdo	Store Rounded Accumulator	1	1	None
71	SE	SE Ws,Wnd	Wnd = sign-extended Ws	1	1	C,N,Z
72	SETM	SETM f	f = 0xFFFF	1	1	None
		SETM WREG	WREG = 0xFFFF	1	1	None
		SETM Ws	Ws = 0xFFFF	1	1	None
73	SFTAC	SFTAC Acc,Wn	Arithmetic Shift Accumulator by (Wn)	1	1	OA,OB,OAB, SA,SB,SAB
		SFTAC Acc,#Slit6	Arithmetic Shift Accumulator by Slit6	1	1	OA,OB,OAB, SA,SB,SAB

Note 1: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 30-10: DC CHARACTERISTICS: DOZE CURRENT (I_{DOZE})

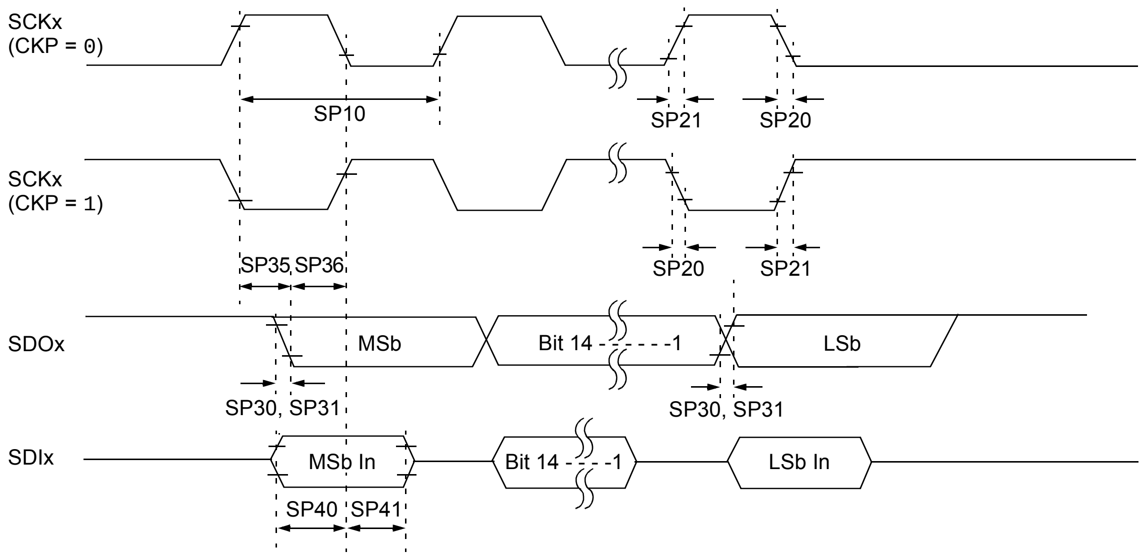
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Parameter No.	**Typ.**	**Max.**	**Doze Ratio**	**Units**	**Conditions**		
Doze Current (I_{DOZE})(1)							
DC73a(2)	20	40	1:2	mA	-40°C	3.3V	F_{OSC} = 140 MHz
DC73g	10	22	1:128	mA			
DC70a(2)	20	40	1:2	mA	+25°C	3.3V	F_{OSC} = 140 MHz
DC70g	10	22	1:128	mA			
DC71a(2)	20	40	1:2	mA	+85°C	3.3V	F_{OSC} = 140 MHz
DC71g	10	22	1:128	mA			
DC72a(2)	20	40	1:2	mA	+125°C	3.3V	F_{OSC} = 120 MHz
DC72g	10	22	1:128	mA			

Note 1: I_{DOZE} is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all I_{DOZE} measurements are as follows:

- Oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating or being clocked (all defined PMDx bits are set)
- CPU is executing `while(1)` statement
- JTAG is disabled

2: These parameter are characterized but not tested in manufacturing.

FIGURE 30-14: SPI1, SPI2 AND SPI3 MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING CHARACTERISTICS(1,2)



Note 1: Pertaining to SPI3: dsPIC33EPXXXGS702, dsPIC33EPXXXGSX04 and dsPIC33EPXXXGSX05 devices with a remappable SCK3 pin.

2: Refer to Figure 30-1 for load conditions.

TABLE 30-34: SPI1, SPI2 AND SPI3 MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING REQUIREMENTS(5)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCKx Frequency	—	—	9	MHz	-40ºC to +125ºC **(Note 3)**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

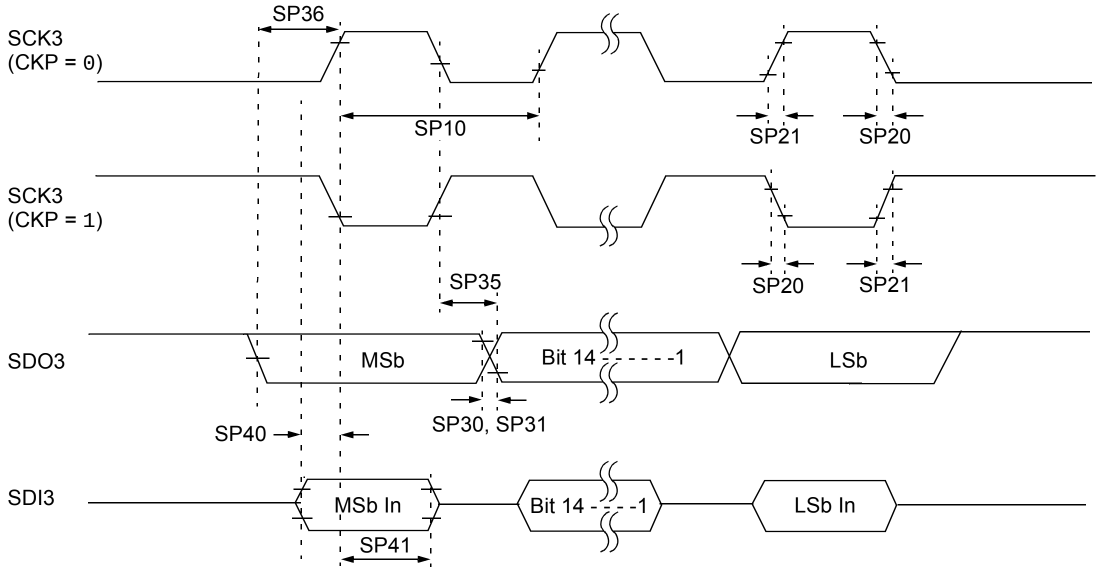
2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 111 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

5: Pertaining to SPI3: dsPIC33EPXXXGS702, dsPIC33EPXXXGSX04 and dsPIC33EPXXXGSX05 devices with a remappable SCK3 pin.

FIGURE 30-21: SPI3 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING CHARACTERISTICS(1,2)



Note 1: For dsPIC33EPXXXGSX06 and dsPIC33EPXXXGSX08 devices with a fixed SCK3 pin.
2: Refer to Figure 30-1 for load conditions.

TABLE 30-41: SPI3 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING REQUIREMENTS(5)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK3 Frequency	—	—	25	MHz	**(Note 3)**
SP20	TscF	SCK3 Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCK3 Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO3 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO3 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO3 Data Output Valid after SCK3 Edge	—	6	20	ns	
SP36	TdoV2sc, TdoV2scL	SDO3 Data Output Setup to First SCK3 Edge	20	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI3 Data Input to SCK3 Edge	20	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI3 Data Input to SCK3 Edge	15	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.
2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.
3: The minimum clock period for SCK3 is 100 ns. The clock generated in Master mode must not violate this specification.
4: Assumes 50 pF load on all SPI3 pins.
5: For dsPIC33EPXXXGSX06 and dsPIC33EPXXXGSX08 devices with a fixed SCK3 pin.

TABLE 30-55: DACx MODULE SPECIFICATIONS

AC/DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(2) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
DA01	EXTREF	External Voltage Reference(1)	1	—	AVDD	V	
DA02	CVRES	Resolution		12		bits	
DA03	INL	Integral Nonlinearity Error	-16	-12	0	LSB	
DA04	DNL	Differential Nonlinearity Error	-1.8	±1	1.8	LSB	
DA05	EOFF	Offset Error	-8	3	15	LSB	
DA06	EG	Gain Error	-1.2	-0.5	0	%	
DA07	TSET	Settling Time(1)	—	700	—	ns	Output with 2% of desired output voltage with a 10-90% or 90-10% step

Note 1: Parameters are for design guidance only and are not tested in manufacturing.
2: The DACx module is functional at VBORMIN < VDD < VDDMIN, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

TABLE 30-56: DACx OUTPUT (DACOUTx PIN) SPECIFICATIONS

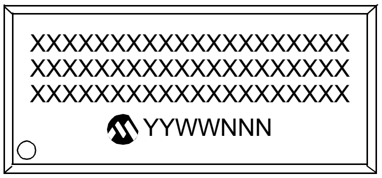
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(1) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
DA11	RLOAD	Resistive Output Load Impedance	10K	—	—	Ohm	
DA11a	CLOAD	Output Load Capacitance	—	—	35	pF	Including output pin capacitance
DA12	IOUT	Output Current Drive Strength	—	300	—	μA	Sink and source
DA13	VRANGE	Output Drive Voltage Range at Current Drive of 300 μA	AVSS + 250 mV	—	AVDD – 900 mV	V	
DA14	VLRANGE	Output Drive Voltage Range at Reduced Current Drive of 50 μA	AVSS + 50 mV	—	AVDD – 500 mV	V	
DA15	IDD	Current Consumed when Module is Enabled	—	—	1.3 x IOUT	μA	Module will always consume this current, even if no load is connected to the output
DA30	VOFFSET	Input Offset Voltage	—	±5	—	mV	

Note 1: The DACx module is functional at VBORMIN < VDD < VDDMIN, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

32.0 PACKAGING INFORMATION

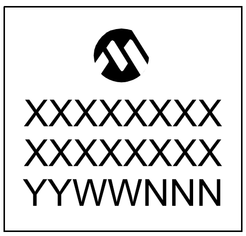
32.1 Package Marking Information

28-Lead SOIC (7.50 mm)



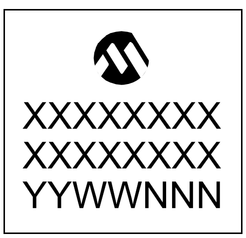
Example

28-Lead UQFN (6x6x0.55 mm)



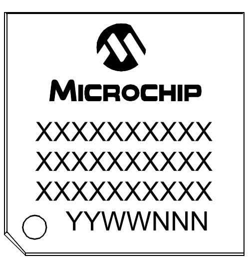
Example

28-Lead QFN-S (6x6x0.9 mm)

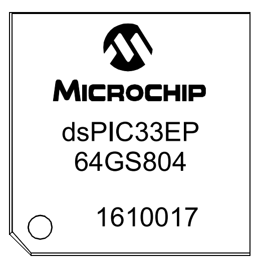


Example

44-Lead TQFP (10x10x1 mm)



Example



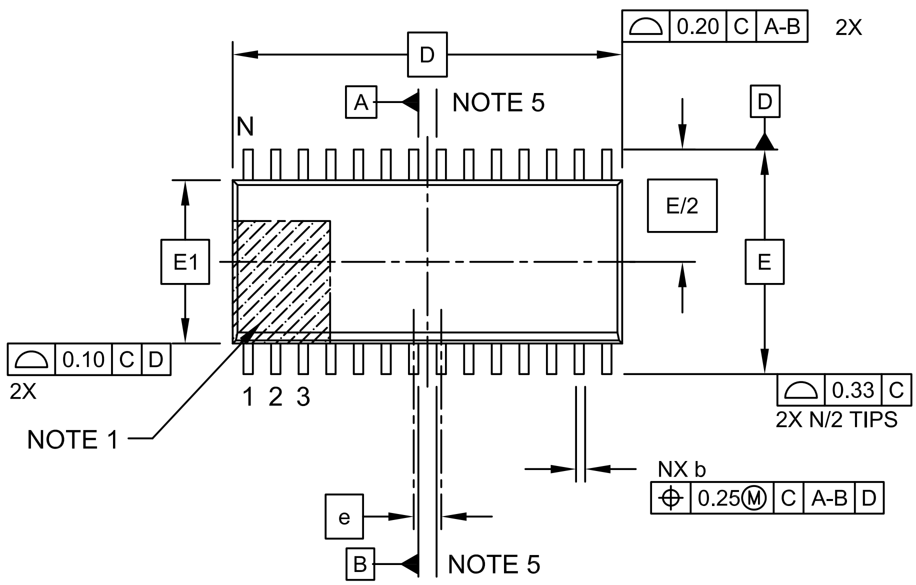
Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

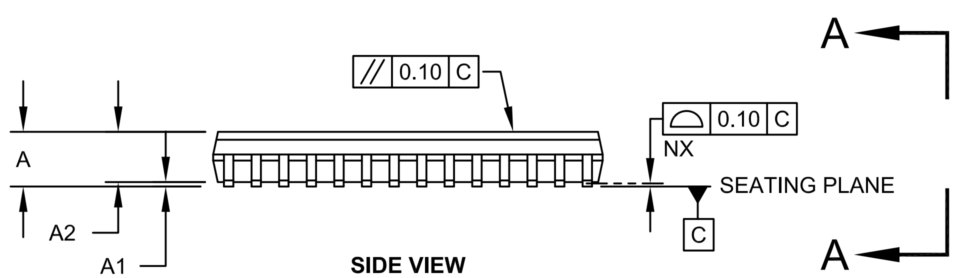
32.2 Package Details

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

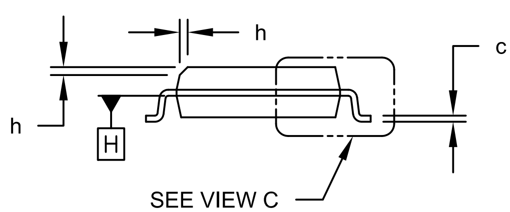
Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

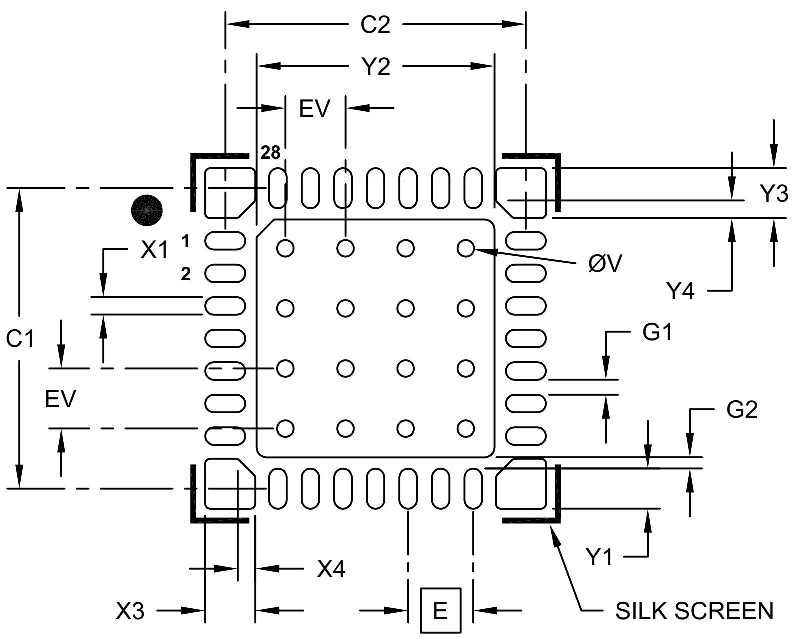


VIEW A-A

Microchip Technology Drawing C04-052C Sheet 1 of 2

28-Lead Ultra Thin Plastic Quad Flat, No Lead Package (2N) - 6x6x0.55 mm Body [UQFN] With 4.65x4.65 mm Exposed Pad and Corner Anchors

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	X2			4.75
Optional Center Pad Length	Y2			4.75
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.35
Contact Pad Length (X28)	Y1			0.80
Corner Anchor (X4)	X3			1.00
Corner Anchor (X4)	Y3			1.00
Corner Anchor Chamfer (X4)	X4			0.35
Corner Anchor Chamfer (X4)	Y4			0.35
Contact Pad to Pad (X28)	G1	0.20		
Contact Pad to Center Pad (X28)	G2	0.20		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2385B

Note: Corner anchor pads are not connected internally and are designed as mechanical features when the package is soldered to the PCB.